### 504031623 09/30/2016

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
HIROHIKO WATANABE	07/22/2016
SHUNSUKE SAITO	07/22/2016
MASAHIRO ONO	07/22/2016
TAKASHI WATANABE	07/22/2016
SHINJI SANO	07/22/2016
KAZUNAGA ONISHI	07/22/2016

# **RECEIVING PARTY DATA**

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### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15276156

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SIGNATURE:	/David M. Pitcher/
DATE SIGNED:	09/30/2016

**PATENT** REEL: 039912 FRAME: 0591 504031623

# Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif

PATENT REEL: 039912 FRAME: 0592

# U.S. ASSIGNMENT

Docket No.

S&H : 00

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(Insert Name(s) & Address(es) of ASSIGNEE(S))

## FUJI ELECTRIC CO., LTD.

(a) executed on \_

1-1, Tanabeshinden, Kawasaki-ku, Kawasaki-shi, Kanagawa 210-9530 JAPAN

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

# LEAD-FREE SOLDERING METHOD AND SOLDERED ARTICLE

relating to International Patent Application and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date of execution of application, if not concurrent)

(b) filed on	Any registered attorney of STAAS & HALSEY LLP, 1201 New York Avenue, N.W., Suite 700 Washington, D.C. 20005 (202/434-1500)
Serial No.:	is hereby authorized to insert in (b) the specified data, when known.
enewal, substitute, reissue or reexamination applicat	United States granted on said application and any continuation, division, ion based thereon, for the full term or terms for which the said Letters Patent(s) (collectively, hereinafter, "said application(s) and Letters Patent(s)").
ASSIGNEE, to do all acts which the ASSIGNEE may enforcing protection for said invention, including in the etters Patent(s), in any interference, reissue, reexam proceeding which may arise or be declared in relation	by said ASSIGNEE and without charge to but at the expense of said deem necessary, desirable or expedient, for securing, maintaining and a preparation and prosecution of said application(s) and the issuance of said nination, or public use proceeding, and in any litigation or other legal to same, such acts to include but not be limited to executing all papers, ing all rightful oaths, providing sworn testimony, and obtaining and producing
IN WITNESS WHEREOF, the undersigned invento (Typed Name & Signature of Inventor(s))	(Date)
HIVOLIFO WATARABE)	2016.7.22
2) Shun Guko Saito	2016.7.22
Masahiro DNO (Masahiro ONO)	<u>2016, 7, 22</u>
(Takashi WATANABE)	
(Shinji SANO)	2016.7.22
(Kazunaga ONISHI)	2016.7.22

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relating to International Patent Application and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on	(Insert date of execution of application, if not concurrent)
(b) filed on	Any registered attorney of STAAS & HALSEY LLP, 1201 New York Avenue, N.W., Suite 700 Washington, D.C. 20005 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.
substitute, reissue or reexamination application based t	nited States granted on said application and any continuation, division, renew thereon, for the full term or terms for which the said Letters Patent(s) may be sely, hereinafter, "said application(s) and Letters Patent(s)").
to do all acts which the ASSIĞNEE may deem necessar said invention, including in the preparation and prosecu interference, reissue, reexamination, or public use proc	
1)(Hirohiko WATANABE)	
2)(Shunsuke SAITO)	
3)(Masahiro ONO)	
4) Ta Kashi WATANABE (Takashi WATANABE)  5) Shingi Samo	2016:7.22
Shinji Sano	2016. 7.22

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